1. Wafer edge detection
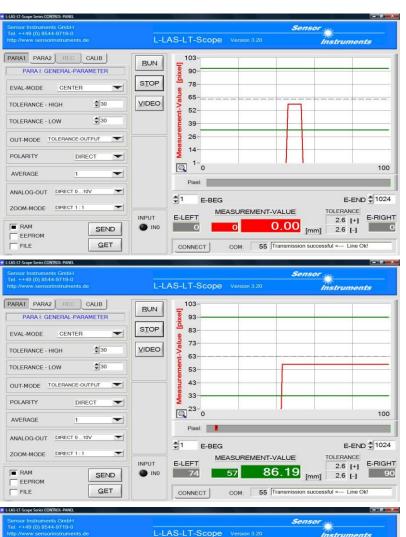
The edges of wafers with a thickness of 80 µm should be detected. For this purpose a laser displacement sensor type **L-LAS-LT-110-HD2** is used. The distance of the sensor to the wafer edges is around 90mm and the laser spot size at this distance is around 50 µm. The edges can be proper detected as shown in the screen shots.